WHAT IS CLAIMED IS:

1. A inspecting device for a semiconductor wafer comprising:

a holding unit which holds a wafer;

an aligner unit which detects a cutout position and a center position of the wafer held by the holding unit and obtains position determining data of the wafer;

an observing unit for magnifying and observing fine patterns on the wafer, the observing unit being disposed at a position where the wafer held by the holding unit can be observed;

a moving unit which relatively moves the holding unit with respect to the observing unit; and

a control unit which controls the moving unit to move the holding unit based on the obtained position data so that the fine patterns at a desired position can be observed.

2. The inspecting device according to claim 1, wherein the moving unit includes:

a rotating unit which relatively rotates the holding unit with respect to the observing unit; and

a horizontally moving unit which relatively moves the holding unit with respect to the observing unit in a substantially horizontally direction.

3. The inspecting device according to claim 1, wherein

the moving unit includes a rotating unit which relatively rotates the holding unit with respect to the aligner unit, and

the control unit controls the rotating unit to rotating the holding unit every predetermined angle and detects the cutout position and the center position with the aligner unit by obtaining distances from a rotational center to an edge of the wafer at each predetermined angle.

4. The inspecting device according to claim 1, wherein

the observing unit includes a photograph unit which captures an image of the fine pattern on the wafer, and

the control unit control the moving unit to move the holding unit based on the image captured by the photograph unit.

5. The inspecting device according to claim 1, wherein

the observing unit includes a photograph unit which captures an image of the fine pattern on the wafer, and

the inspecting device further comprises a computing unit which judges if the wafer is proper based on the image captured by the photograph unit.

6. A inspecting device for a semiconductor wafer comprising:

a holding unit which holds the wafer;

an aligner unit which detects a cutout position and a center position of the wafer held by the holding unit;

an observing unit for magnifying and observing fine patterns on the wafer, the observing unit being disposed at a position where the wafer held by the holding unit can be observed;

a rotating unit which relatively rotates the holding unit with respect to the aligner unit and the observing unit;

a horizontally moving unit which relatively moves the holding unit with respect to the observing unit in a substantially horizontally direction; and

a control unit which controls the rotating unit to rotate the holding unit every predetermined angle, detects the cutout position and the center position with the aligner unit by obtaining distances from a rotational center to an edge of the wafer at each predetermined angle, and controls the rotating unit and the horizontally moving unit to move the holding unit based on the obtained position data so that the fine patterns at a desired position can be observed.